TOSHIBA

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ($L^2-\pi$ -MOSV)

2 S K 2 6 1 5

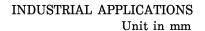
HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS

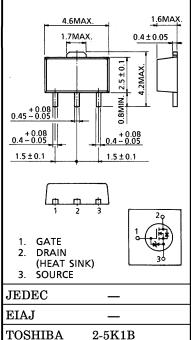
DC-DC CONVERTER, RELAY DRIVE AND MOTOR DRIVE **APPLICATIONS**

- Low Drain-Source ON Resistance : $R_{DS(ON)} = 0.23\Omega$ (Typ.) •
- High Forward Transfer Admittance : $|Y_{fs}| = 2.0S$ (Typ.)
- Low Leakage Current : $I_{DSS} = 100 \mu A$ (Max.) ($V_{DS} = 60V$)
- : $V_{th} = 0.8 \sim 2.0 V$ ($V_{DS} = 10V$, $I_D = 1mA$) Enhancement-Mode

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIST	SYMBOL	RATING	UNIT	
Drain-Source Voltage	V _{DSS}	60	V	
Drain-Gate Voltage (R _{GS} :	V _{DGR}	60	v	
Gate-Source Voltage	V _{GSS}	± 20	v	
Drain Current	DC	ID	2	А
	Pulse	I _{DP}	6	А
Drain Power Dissipation (PD	0.5	W	
Drain Power Dissipation	PD*	1.5	W	
Channel Temperature	T _{ch}	150	°C	
Storage Temperature Rang	T_{stg}	$-55 \sim 150$	°C	





Weight : 0.05g (Typ.)

* : Mounted on ceramic substrate ($600 \text{mm}^2 \times 0.8t$)

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT	
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	250	°C/W	

This transistor is an electrostatic sensitive device. Please handle with caution.





961001EAA2

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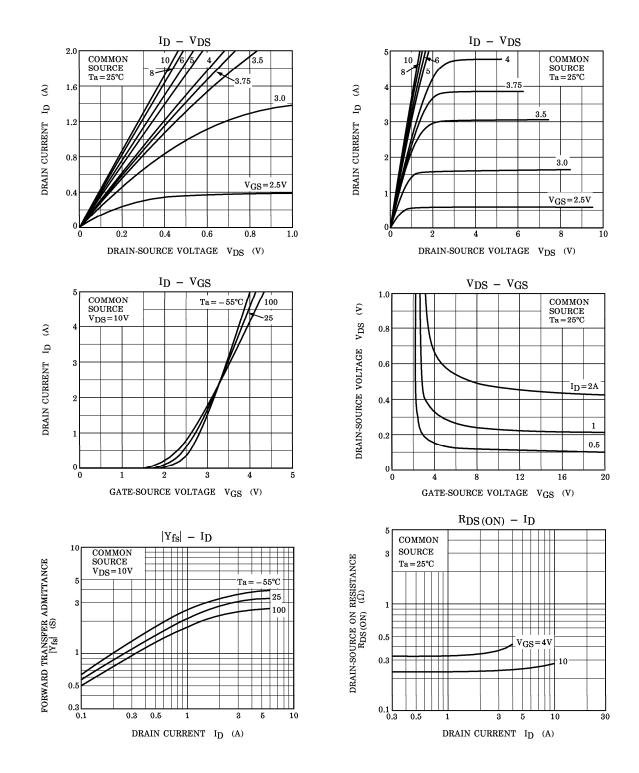
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CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		IGSS	$V_{GS} = \pm 16V, V_{DS} = 0V$	_		±10	μA
Drain Cut-of	f Current	IDSS	$V_{DS} = 60V, V_{GS} = 0V$		_	100	μA
Drain-Source Breakdown Voltage		V (BR) DSS	$I_D=10mA$, $V_{GS}=0V$	60	_	_	v
Gate Thresh	Gate Threshold Voltage		$V_{DS} = 10V, I_D = 1mA$	0.8		2.0	V
Drain-Source ON Resistance		V _{th} R _{DS (ON)}	$V_{GS}=4V, I_{D}=1A$	—	0.33	0.44	Ω
			$V_{GS} = 10V, I_D = 1A$	_	0.23	0.30	
Forward Tra Admittance	nsfer	Y _{fs}	$V_{DS}=10V, I_{D}=1A$	1.0	2.0	_	s
Input Capacitance		Ciss		_	150	_	
Reverse Transfer Capacitance		C _{rss}	V _{DS} =10V, V _{GS} =0V, f=1MHz	_	25	_	pF
Output Capacitance		C _{oss}		_	70	_	
Switching Time	Rise Time	tr	$V_{GS} \stackrel{10V}{}_{0V} \prod \stackrel{I_D=1A}{}_{I_D=1} V_{OUT}$		25	_	
	Turn-on Time	t _{on}	$\begin{array}{c} \mathbf{C} \\ $	_	30	_	ns
	Fall Time	tf		_	50	_	
	Turn-off Time	toff	$V_{IN}: t_r, t_f < 5ns,$ Duty $\leq 1\%, t_w = 10 \mu s$	_	150	_	
Total Gate Charge (Gate- Source Plus Gate-Drain)		\mathbf{Q}_{g}		_	6.0	_	
Gate-Source Charge		$Q_{\rm gs}$	$V_{DD} = 48V, V_{GS} = 10V, I_D = 2A$		4.6	_	nC
Gate-Drain ("Miller") Charge		Q _{gd}		_	1.4	_	

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	IDR	_	_	_	2	A
Pulse Drain Reverse Current	IDRP	_	_	_	6	A
Diode Forward Voltage	VDSF	$I_{DR}=2A, V_{GS}=0V$		_	-1.5	V
Reverse Recovery Time	t _{rr}	$I_{DR}=2A, V_{GS}=0V$		100	_	ns
Reverse Recovered Charge	Q _{rr}	$dI_{DR}/dt = 50A/\mu s$	_	40	_	μC

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